

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (Original) A method of assembling a packaged high frequency circuit module including the steps of :  
  
providing a ceramic substrate having one or more elongate stub walls projecting from a planar surface thereof;  
  
firing the ceramic substrate;  
  
processing the surface of the substrate until the planar surfaces of the elongate stub walls are uniform and parallel;  
  
applying a conductive adhesive to the processed surfaces of the stub walls;  
  
placing a housing lid over the substrate, the lid having one or more members projecting from a planar surface thereof so that the members align with the stub walls of the substrate to form a composite structure.
2. (Original) A method according to claim 1, wherein the stub walls extend, at least partially, around the periphery of the planar surface of the substrate.
3. (Currently Amended) A method according to ~~claims 1 or 2~~ claim 1, wherein one or more stub walls project from the internal surface of the substrate.

4. (Currently Amended) A method according to ~~any preceding claim~~ claim 1, wherein the projection of the stub walls from the planar surface of the substrate is proportional to predetermined surface distortion values for such a substrate.
5. (Currently Amended) A method according to ~~any preceding claim~~ claim 1, wherein processing the surface comprises one or more of grinding, lapping or polishing the surface.
6. (Original) A method according to claim 1, further comprising the steps of applying pressure to the composite structure and curing the conductive adhesive.
7. (Original) A method according to claim 1, wherein the elongate stub walls project from the upper planar surface of the substrate.
8. (Original) A method according to claim 1, wherein the elongate stub walls project from the lower planar surface of the substrate.
9. (Original) A high frequency circuit module comprising:

a ceramic substrate having one or more elongate stub walls projecting from a planar surface thereof, the planar surfaces of the stub walls having been processed so that they are uniform and parallel;

a conductive adhesive layer on the processed surfaces of the stub walls; and

a housing lid mounted over the substrate, the lid having one or more members projecting from a planar surface thereof so that the members align with the stub walls of the substrate to form a composite structure.

10. (New) A method according to claim 2, wherein one or more stub walls project from the internal surface of the substrate.
11. (New) A method according to claim 2, wherein the projection of the stub walls from the planar surface of the substrate is proportional to predetermined surface distortion values for such a substrate.
12. (New) A method according to claim 3, wherein the projection of the stub walls from the planar surface of the substrate is proportional to predetermined surface distortion values for such a substrate.
13. (New) A method according to claim 2, wherein processing the surface comprises one or more of grinding, lapping or polishing the surface.

14. (New) A method according to claim 3, wherein processing the surface comprises one or more of grinding, lapping or polishing the surface.
15. (New) A method according to claim 4, wherein processing the surface comprises one or more of grinding, lapping or polishing the surface.